



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



DY2J25000L

Silicon epitaxial planar type

For high surge protection
 Capability of withstanding a high surge type

■ Features

- High ESD
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: 25

■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Peak pulse power*1	Ppp	450	W
Peak pulse current*1	Ipp	9	A
Maximum peak reverse voltage	VRM	18	V
Total power dissipation*2	PT	200	mW
Electrostatic discharge*3	ESD	±30	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

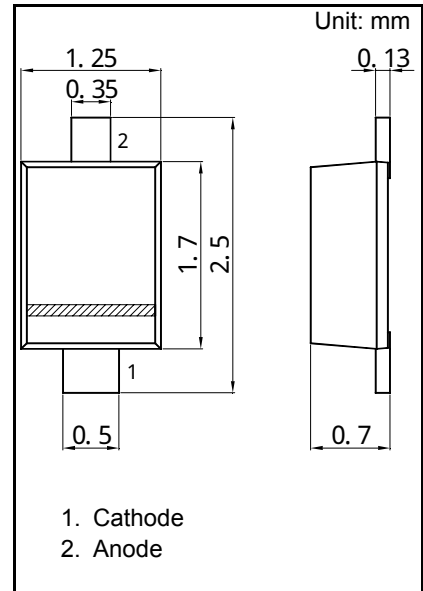
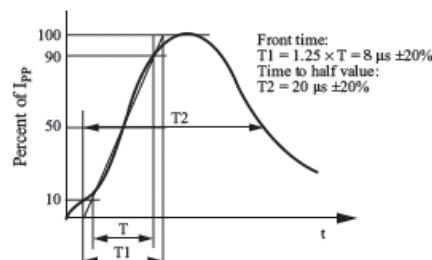
Note) *1: Test method : IEC61000-4-5 (tp = 8/20ms, Unrepeated)
 *2: Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm)
 Solder in (Recommended land pattern)
 *3: Test method:IEC61000_4_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)

■ Electrical Characteristics Ta = 25 °C ± 3 °C

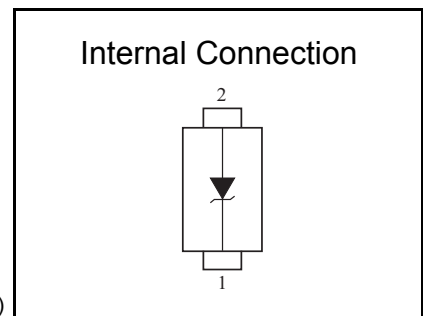
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Breakdown voltage*1	VBR	IR = 1 mA	22.50	25.00	27.50	V
Reverse current	IR	VR = 18.0 V			10.0	μA
Clamping voltage*2	VC	IPP = 9.0 A, tp = 8/20 μs			50.0	V
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		97.0		pF

Note) 1 Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

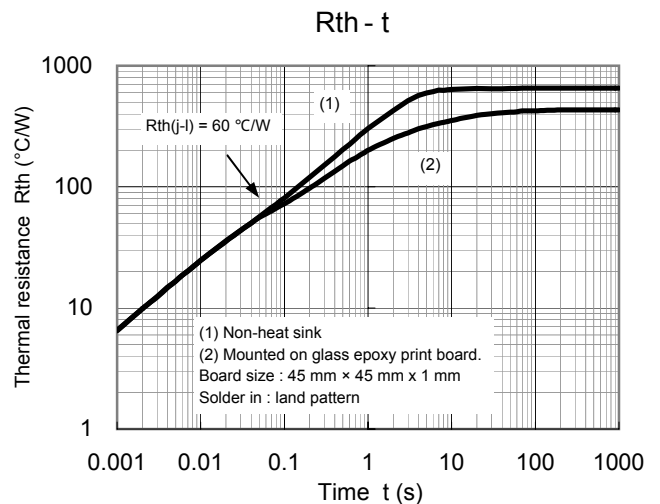
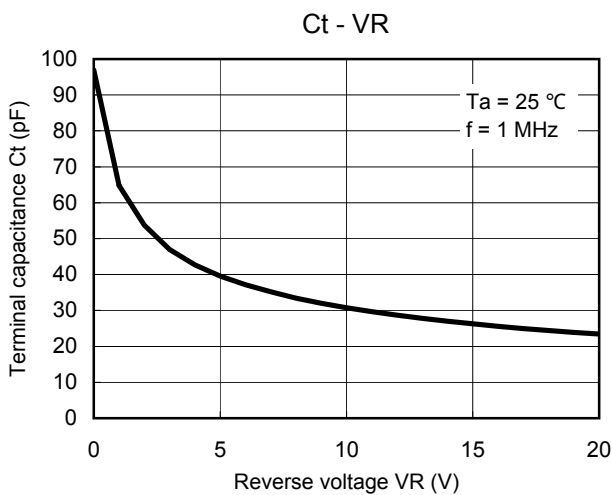
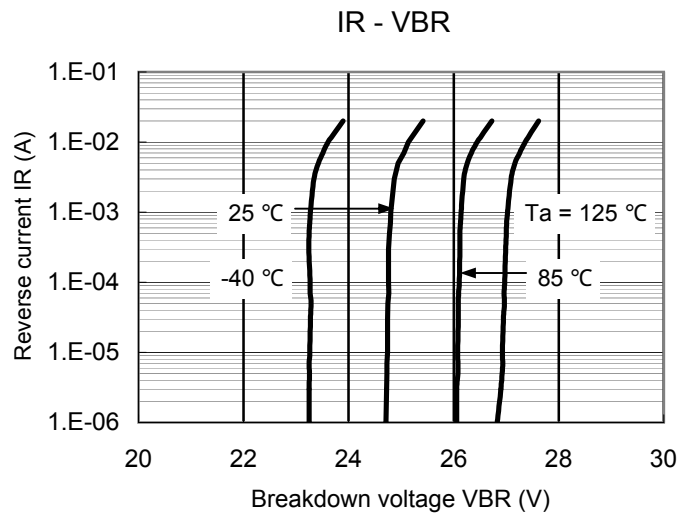
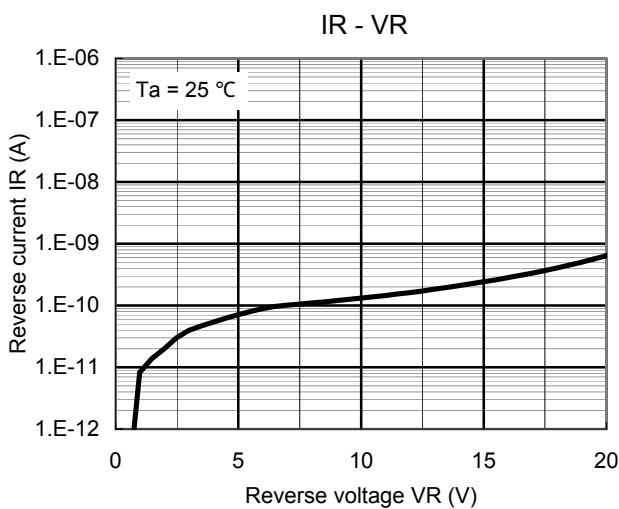
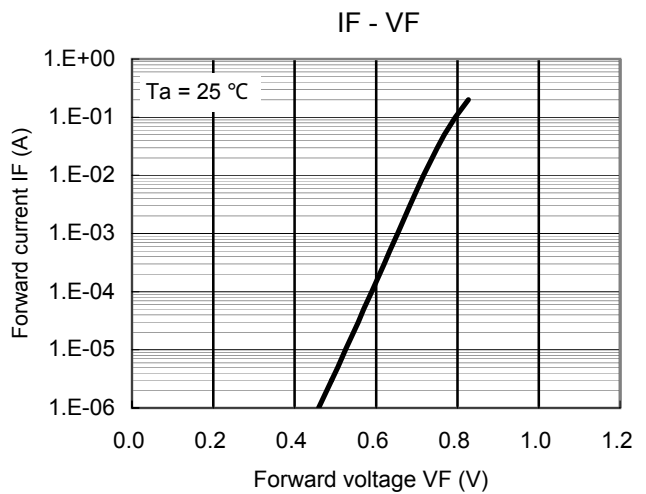
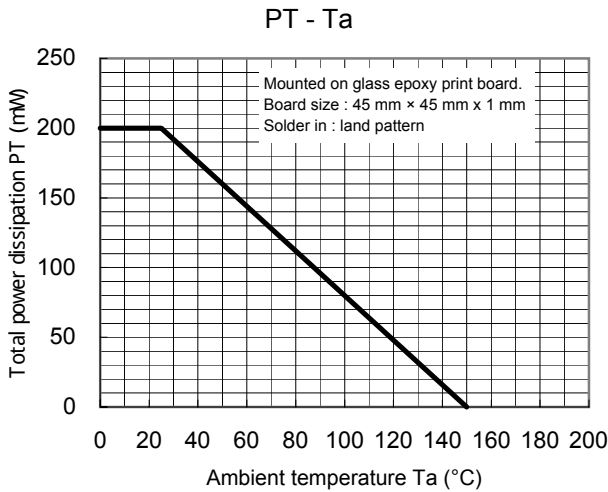
2. *1: VBR guaranteed 20 ms after current flow.
 *2: Pulse Waveform



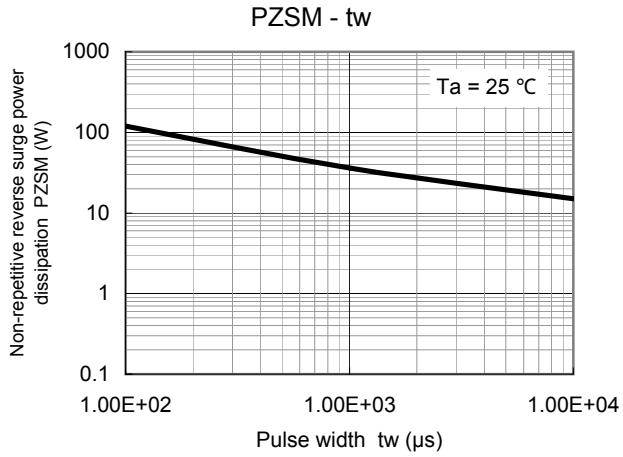
Panasonic	SMini2-F5-B
JEITA	SC-90A
Code	—



Technical Data (reference)

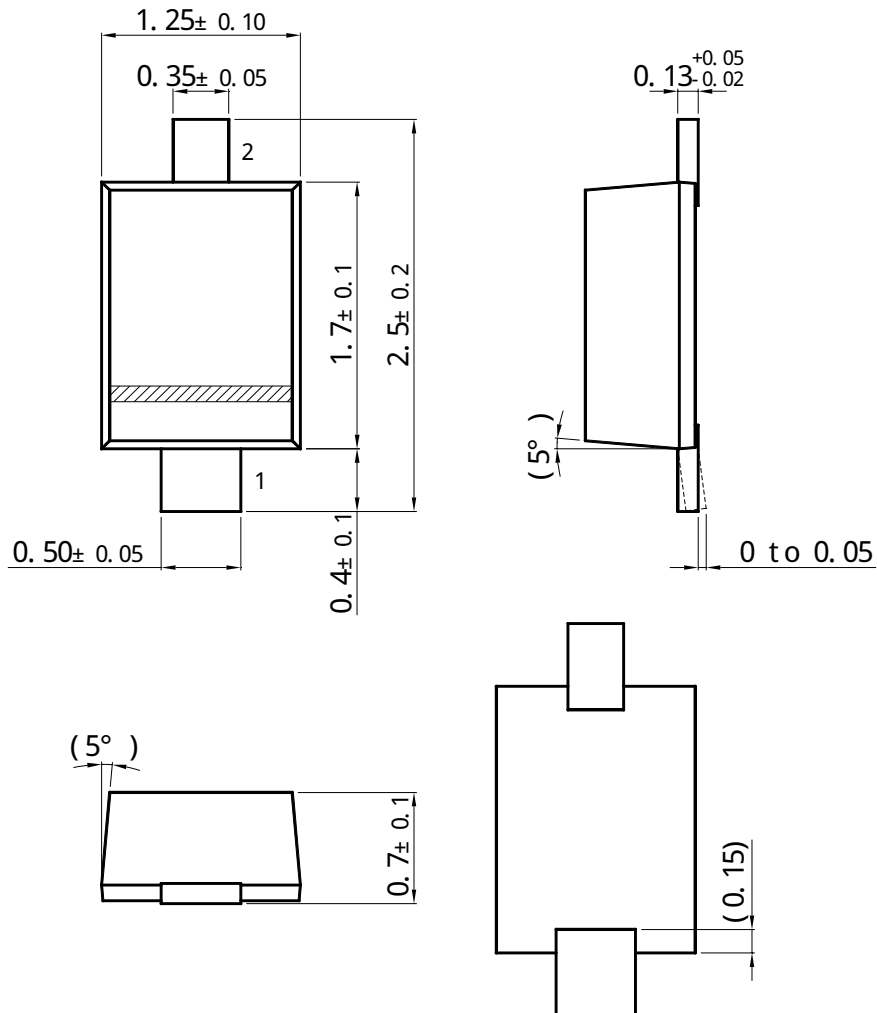


Technical Data (reference)

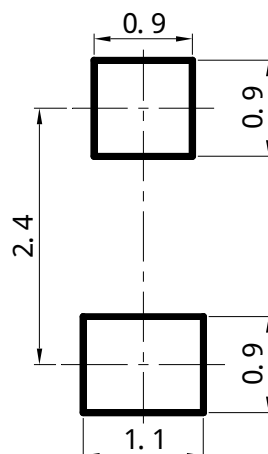


SMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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